

LNPT[™] THERMOTUF[™] COMPOUND WF008N

DESCRIPTION

LNP THERMOTUF WF008N compound is based on Polybutylene Terephthalate (PBT) resin containing 40% glass fiber. Added features of this grade include: Impact Modified, Good Metal Bonding Strength and Good Chemical Resistance targeted for Nano-Molding Technology (NMT) applications.

GENERAL INFORMATION

Features	Chemical Resistance, Nano molding technology, High stiffness/Strength, Impact resistant, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polybutylene Terephthalate (PBT)
Processing Techniques	Injection Molding

INDUSTRY

SUB INDUSTRY

Consumer	Personal Accessory
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20230607

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, brk, Type I, 5 mm/min	133	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	2.4	%	ASTM D638
Tensile Modulus, 5 mm/min	11600	MPa	ASTM D638
Flexural Stress, brk, 1.3 mm/min, 50 mm span	205	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	11000	MPa	ASTM D790
Tensile Stress, break, 5 mm/min	134	MPa	ISO 527
Tensile Strain, break, 5 mm/min	2.5	%	ISO 527
Tensile Modulus, 1 mm/min	11700	MPa	ISO 527
Flexural Stress, break, 2 mm/min	217	MPa	ISO 178
Flexural Modulus, 2 mm/min	11200	MPa	ISO 178
Bonding Strength ("T" treatment, shear type)	34	MPa	ISO 19095
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	960	J/m	ASTM D4812
Izod Impact, notched, 23°C	145	J/m	ASTM D256
Izod Impact, notched, -30°C	106	J/m	ASTM D256
Izod Impact, unnotched 80*10*4 +23°C	59	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	14	kJ/m ²	ISO 180/1A
Izod Impact, notched 80*10*4 -30°C	11	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 1.82 MPa, 3.2mm, unannealed	193	°C	ASTM D648
HDT, 0.45 MPa, 3.2 mm, unannealed	217	°C	ASTM D648

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	196	°C	ISO 75/Af
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	218	°C	ISO 75/Bf
CTE, -40°C to 40°C, flow	1.9E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, xflow	8.7E-05	1/°C	ASTM E831
CTE, 23°C to 50°C, flow	1.7E-05	1/°C	ASTM E831
CTE, 23°C to 50°C, xflow	9.0E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, flow	1.8E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	8.6E-05	1/°C	ISO 11359-2
CTE, 23°C to 50°C, flow	1.7E-05	1/°C	ISO 11359-2
CTE, 23°C to 50°C, xflow	8.9E-05	1/°C	ISO 11359-2
Relative Temp Index, Elec ⁽²⁾	75	°C	UL 746B
Relative Temp Index, Mech w/impact ⁽²⁾	75	°C	UL 746B
Relative Temp Index, Mech w/o impact ⁽²⁾	75	°C	UL 746B
PHYSICAL ⁽¹⁾			
Density	1.58	g/cm ³	ISO 1183
Melt Flow Rate, 250°C/5.0 kgf	10	g/10 min	ASTM D1238
Melt Flow Rate, 275°C/5 kgf	22	g/10 min	ASTM D1238
Melt Volume Rate, MVR at 250°C/5.0 kg	7	cm ³ /10 min	ISO 1133
Melt Volume Rate, MVR at 275°C/5 kg	15	cm ³ /10 min	ISO 1133
Mold Shrinkage, flow ⁽³⁾	0.25	%	SABIC method
Mold Shrinkage, xflow ⁽³⁾	0.65	%	SABIC method
ELECTRICAL ⁽¹⁾			
Dielectric Constant, 1.1 GHz	3.78	-	SABIC method
Dielectric Constant, 1.9 GHz	3.76	-	SABIC method
Dielectric Constant, 5 GHz	3.73	-	SABIC method
Dielectric Constant, 10 GHz	3.80	-	SABIC method
Dissipation Factor, 1.1 GHz	0.0104	-	SABIC method
Dissipation Factor, 1.9 GHz	0.0096	-	SABIC method
Dissipation Factor, 5 GHz	0.0091	-	SABIC method
Dissipation Factor, 10 GHz	0.0082	-	SABIC method
FLAME CHARACTERISTICS ⁽²⁾			
UL Yellow Card Link	E207780-104061413	-	-
UL Recognized, 94HB Flame Class Rating	≥0.7	mm	UL 94
INJECTION MOLDING ⁽⁴⁾			
Drying Temperature	100 – 120	°C	
Drying Time	2 – 4	Hrs	
Drying Time (Cumulative)	8	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	250 – 270	°C	
Nozzle Temperature	255 – 275	°C	
Front - Zone 3 Temperature	250 – 270	°C	
Middle - Zone 2 Temperature	250 – 270	°C	
Rear - Zone 1 Temperature	240 – 260	°C	
Hopper Temperature	40 – 60	°C	
Mold Temperature ⁽⁵⁾	100 – 160	°C	



- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.
- (3) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.
- (5) Suggest to use narrow mold temperature 140C~160C for NMT application.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

MORE INFORMATION

For curve data and CAE cards, please visit and register at <https://materialfinder.sabic-specialties.com>

DISCLAIMER

Any sale by SABIC, its subsidiaries and affiliates (each a "seller"), is made exclusively under seller's standard conditions of sale (available upon request) unless agreed otherwise in writing and signed on behalf of the seller. While the information contained herein is given in good faith, SELLER MAKES NO WARRANTY, EXPRESS OR IMPLIED, INCLUDING MERCHANTABILITY AND NON-INFRINGEMENT OF INTELLECTUAL PROPERTY, NOR ASSUMES ANY LIABILITY, DIRECT OR INDIRECT, WITH RESPECT TO THE PERFORMANCE, SUITABILITY OR FITNESS FOR INTENDED USE OR PURPOSE OF THESE PRODUCTS IN ANY APPLICATION. Each customer must determine the suitability of seller materials for the customer's particular use through appropriate testing and analysis. No statement by seller concerning a possible use of any product, service or design is intended, or should be construed, to grant any license under any patent or other intellectual property right.